# Green Journals

International Approved Journals

## Journal Information

| | |
|---|---|
| **Journal Title** | Microelectronics Reliability |
| **Publisher** | Elsevier Ltd |
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| **E-ISSN** | |
| **Database** | SCOPUS |
| **Domain** | Physical Sciences, Social Sciences |

## Classification History

| Year | A+ | A | B | C |
|---|---|---|---|---|
| **2026** | | ✓ | ✓ | |
| **2025** | | ✓ | ✓ | |
| **2024** | | ✓ | ✓ | |
| **2023** | | ✓ | ✓ | |
| **2021/2022** | | ✓ | ✓ | |
| **2020** | | ✓ | ✓ | |
| **2019** | | ✓ | ✓ | |
| **2018** | | ✓ | | |

**Classification:** The table above shows all journal classifications recorded for each classification year in the Green Journals database. A journal may have more than one classification in the same year.

## Recent Articles

**Yield strength–residual stress coupling in fretting-induced electrical degradation of Ag–Ni electrical contact coatings**
2026-12 Vol. 187 Pages 116343
Authors: Xue Zhou, Mingxu Zhang, Guofu Zhai et al.
DOI: 10.1016/j.microrel.2026.116343

**Thermo-mechanical simulation and reliability analysis of 3D-printed stacked memory packages**
2026-12 Vol. 187 Pages 116348
Authors: Doyun Kim, Junwoo Park, Mun Goung Jeong et al.
DOI: 10.1016/j.microrel.2026.116348

**Active thermography-based detection of thermistor joints using difference shadow method and deep learning algorithm**
2026-12 Vol. 187 Pages 116330
Authors: Jiayi Yuan, Zhenzhi He, Bo Sun et al.
DOI: 10.1016/j.microrel.2026.116330

**Maximum likelihood Weibull analysis of repetitive short-circuit stress in asymmetrical trench SiC MOSFETs**
2026-12 Vol. 187 Pages 116322
Authors: Krisztián Kovács, Michal Minárik, Jozef Kozárik et al.
DOI: 10.1016/j.microrel.2026.116322

**Power cycling lifetime model considering chip surface temperature gradient for power semiconductor devices**
2026-12 Vol. 187 Pages 116352
Authors: Erping Deng, Maoyang Pan, Lixin Wu et al.
DOI: 10.1016/j.microrel.2026.116352

**Multiphysics simulation for solder joint reliability analysis and lifetime prediction: A review**
2026-12 Vol. 187 Pages 116351
Authors: Wenliang Qi, Zhaoyang Xue, Yang Xu et al.
DOI: 10.1016/j.microrel.2026.116351

**Investigations on the degradation of IGBT under repetitive short-circuit tests**
2026-12 Vol. 187 Pages 116350
Authors: Yuzheng Huang, Zhonghao Dongye, Binru Zhao et al.
DOI: 10.1016/j.microrel.2026.116350

**RASP: Reliability ab initio simulation package of MOSFETs based on all-state model**
2026-12 Vol. 187 Pages 116340
Authors: Xinjing Guo, Menglin Huang, Shiyou Chen
DOI: 10.1016/j.microrel.2026.116340

**Backside power delivery as a thermal remedy for buried-oxide self-heating in 3 nm complementary Forksheet CMOS**
2026-12 Vol. 187 Pages 116341
Authors: Bhubesh Chander Joshi, Ajeet Kumar
DOI: 10.1016/j.microrel.2026.116341

**Mechanism on solder-IMC crack formation in fine-pitch BGA packages**
2026-12 Vol. 187 Pages 116329
Authors: F.F. Huang, X.Y. Liu, M.L. Huang
DOI: 10.1016/j.microrel.2026.116329